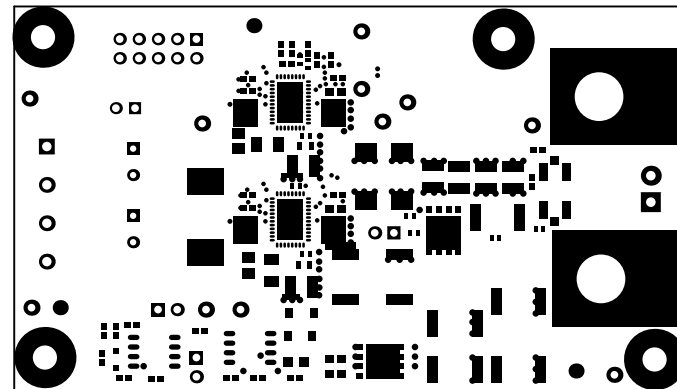
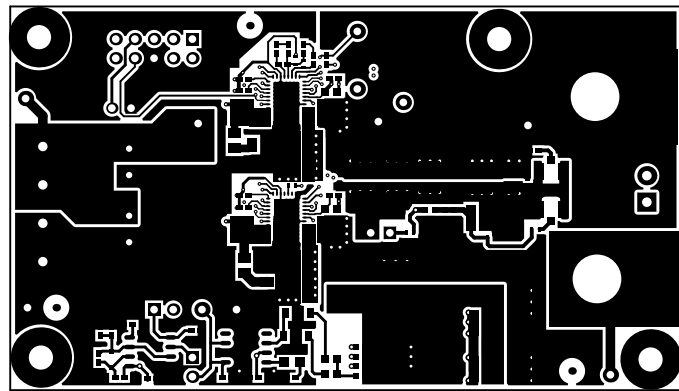


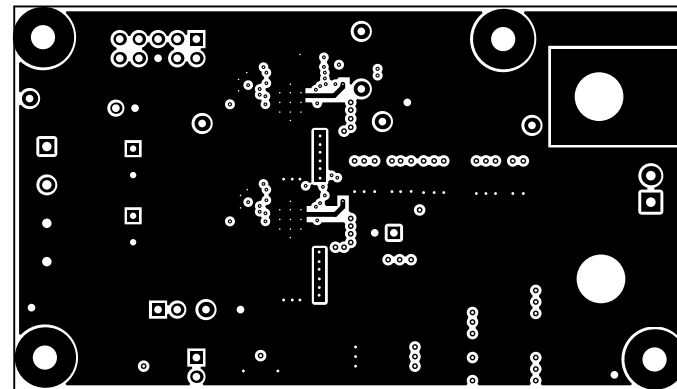
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20292	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP20292		
PLOT NAME = Top Overlay	GENERATED : 8/22/2016 4:06:13 PM	TEXAS INSTRUMENTS	



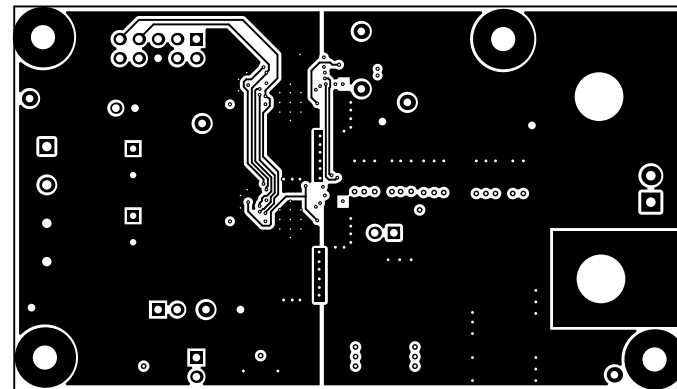
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20292	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP20292		
PLOT NAME = Top Solder Mask	GENERATED : 8/22/2016 4:06:14 PM	TEXAS INSTRUMENTS	



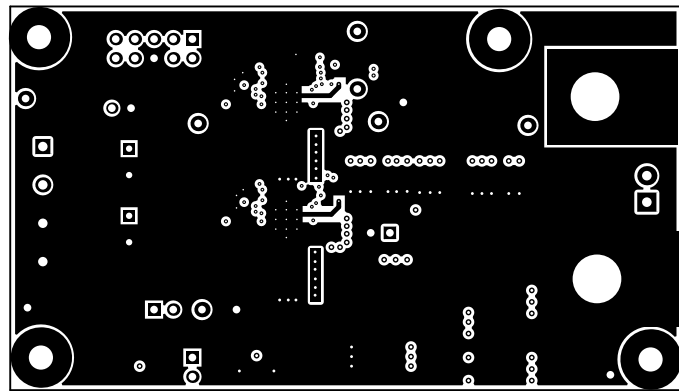
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20292	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP20292		
PLOT NAME = Top Layer	GENERATED : 8/22/2016 4:06:14 PM	TEXAS INSTRUMENTS	



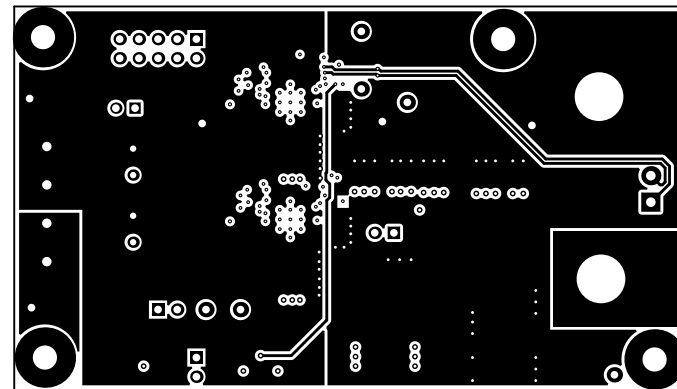
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20292	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP20292		
PLOT NAME = Signal Layer 1	GENERATED : 8/22/2016 4:06:15 PM	TEXAS INSTRUMENTS	



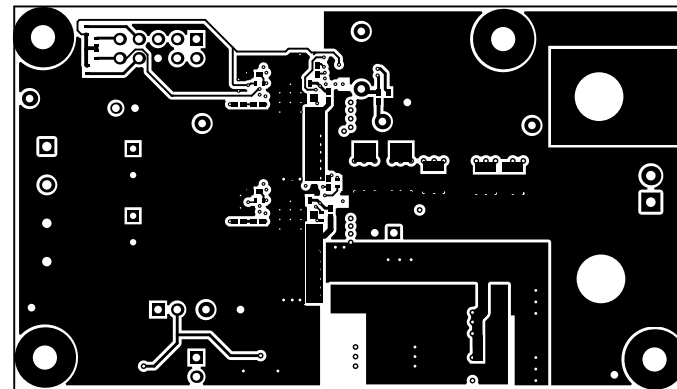
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20292	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP20292		
PLOT NAME = Signal Layer 2	GENERATED : 8/22/2016 4:06:16 PM	TEXAS INSTRUMENTS	



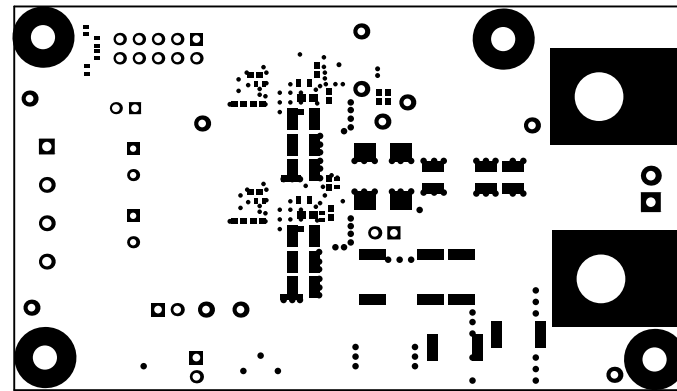
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20292	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP20292		
PLOT NAME = Signal Layer 3	GENERATED : 8/22/2016 4:06:17 PM	TEXAS INSTRUMENTS	



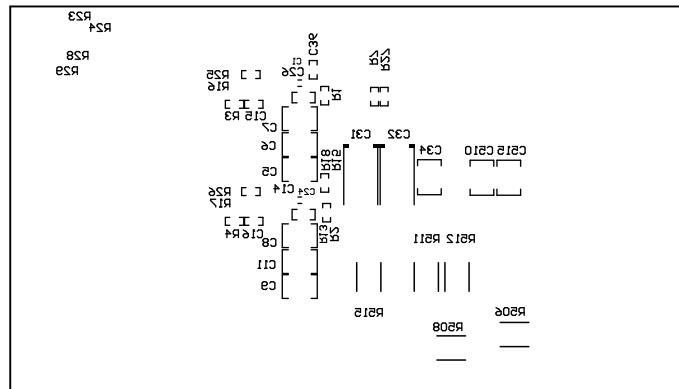
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20292	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP20292		
PLOT NAME = Signal Layer 4	GENERATED : 8/22/2016 4:06:18 PM	TEXAS INSTRUMENTS	



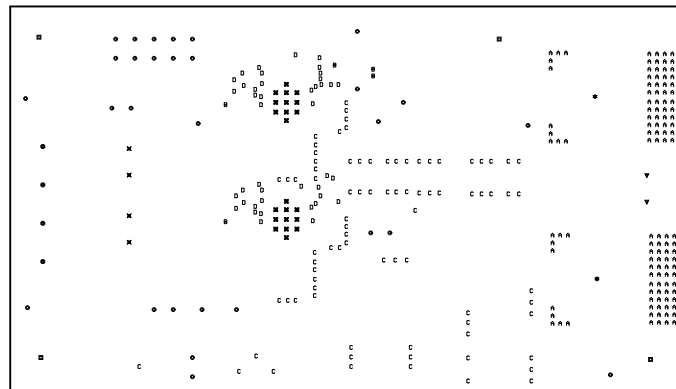
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20292	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP20292		
PLOT NAME = Bottom Layer	GENERATED : 8/22/2016 4:06:19 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20292	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP20292		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/22/2016 4:06:20 PM	TEXAS INSTRUMENTS	

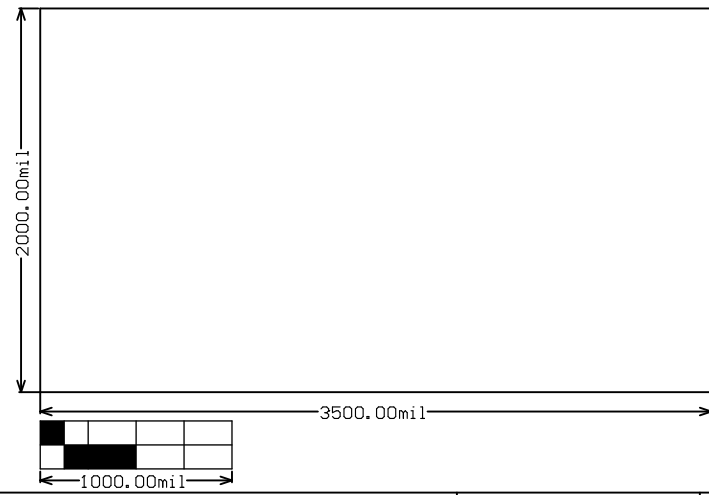


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20292	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP20292		
PLOT NAME = Bottom Overlay	GENERATED : 8/22/2016 4:06:21 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	22	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
D	42	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
B	5	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
C	82	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	
A	116	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	33.00mil (0.838mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	29	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	4	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	2	254.00mil (6.452mm)	PTH	Round	Top Layer - Bottom Layer	
	312 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20292	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP20292		
PLOT NAME = Drill Drawing	GENERATED : 8/22/2016	4:06:22 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20292	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP20292		
PLOT NAME = Board Dimensions	GENERATED : 8/22/2016 4:06:23 PM	TEXAS INSTRUMENTS	

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